

General Description

The BDE-MP26P is a high performance multiprotocol 2.4-GHz wireless module supporting Thread, Zigbee®, Matter, Bluetooth® 5.2 Low Energy, IEEE 802.15.4g, IPv6-enabled smart objects (6LoWPAN), proprietary systems including TI 15.4-Stack (2.4-GHz), and concurrent multiprotocol through a Dynamic Multiprotocol Manager (DMM) driver. The module is optimized for low-power wireless communication and advanced sensing in building security systems, HVAC, medical, wired networking, portable electronics, and home theater & entertainment markets. Please refer to Table 1-1 for variant details.

The module has a low standby current of 0.92 μ A with full 256 KB RAM retention, which enables longer battery life wireless applications. With its integrated PA, the module supports +20 dBm output power with best-in-class transmit current consumption at 101 mA for 2.4-GHz operation. This is suitable for the long-range and low-power applications. It is featured with the Low SER (Soft Error Rate) FIT (Failure-in-time) for long operational lifetime with no disruption for industrial markets with always-on SRAM parity against corruption due to potential radiation events. The device also has an autonomous ultra-low power Sensor Controller CPU with fast wake-up capability. As an example, the sensor controller is capable of 1-Hz ADC sampling at 1- μ A system current.

The module integrates all required system-level hardware components including clocks, balun filter, other passives, and PCB trace antenna or U.FL connector into a small PCB form factor. It is for easy assembly and low-cost PCB design.

Table 1-1. Module Variants

Model Number	Orderable Part Number	Chipset	Flash (KB)	SRAM (KB)	Antenna on 2.4G	On-Board SPI Flash Support	Operating Temperature(°C)
BDE-MP26P	BDE-MP2674P10A32	CC2674P10	1024	296	PCB Trace Antenna	32Mbit	-40 ~ +85
	BDE-MP2674P10U32				U.FL Connector		
	BDE-MP2674P10N32				ANT Pin		
	BDE-MP2674P10A0				PCB Trace Antenna	Not Included	
	BDE-MP2674P10U0				U.FL Connector		
	BDE-MP2674P10N0				ANT Pin		
	BDE-MP2674P10A32-IN				PCB Trace Antenna	32Mbit	-40 ~ +105
	BDE-MP2674P10U32-IN				U.FL Connector		
	BDE-MP2674P10N32-IN				ANT Pin		
	BDE-MP2674P10A0-IN				PCB Trace Antenna	Not Included	
	BDE-MP2674P10U0-IN				U.FL Connector		
	BDE-MP2674P10N0-IN				ANT Pin		
	BDE-MP2652P7A32	CC2652P7	704	152	PCB Trace Antenna	32Mbit	-40 ~ +85
	BDE-MP2652P7U32				U.FL Connector		
	BDE-MP2652P7N32				ANT Pin		
	BDE-MP2652P7A0				PCB Trace Antenna	Not Included	
	BDE-MP2652P7U0				U.FL Connector		
	BDE-MP2652P7N0				ANT Pin		
	BDE-MP2652P7A32-IN				PCB Trace Antenna	32Mbit	-40 ~ +105
	BDE-MP2652P7U32-IN				U.FL Connector		
	BDE-MP2652P7N32-IN				ANT Pin		
	BDE-MP2652P7A0-IN				PCB Trace Antenna	Not Included	
	BDE-MP2652P7U0-IN				U.FL Connector		
	BDE-MP2652P7N0-IN				ANT Pin		

Model Number	Orderable Part Number	Chipset	Flash (KB)	SRAM (KB)	Antenna on 2.4G	On-Board SPI Flash Support	Operating Temperature(°C)
	BDE-MP2651P3A32	CC2651P3	352	40	PCB Trace Antenna	32Mbit	-40 ~ +85
	U.FL Connector						
	ANT Pin						
	PCB Trace Antenna				Not Included		
	U.FL Connector						
	ANT Pin						
	PCB Trace Antenna				32Mbit	-40 ~ +105	
	U.FL Connector						
	ANT Pin						
	PCB Trace Antenna				Not Included		
	U.FL Connector						
	ANT Pin						
	BDE-MP2652PA32	CC2652P	352	88	PCB Trace Antenna	32Mbit	-40 ~ +85
	BDE-MP2652PU32				U.FL Connector		
	BDE-MP2652PN32				ANT Pin		
	BDE-MP2652PA0				PCB Trace Antenna	Not Included	
	BDE-MP2652PU0				U.FL Connector		
	BDE-MP2652PN0				ANT Pin		
	BDE-MP2652PA32-IN				PCB Trace Antenna	32Mbit	-40 ~ +105
	BDE-MP2652PU32-IN				U.FL Connector		
	BDE-MP2652PN32-IN				ANT Pin		
	BDE-MP2652PA0-IN				PCB Trace Antenna	Not Included	
	BDE-MP2652PU0-IN				U.FL Connector		
	BDE-MP2652PN0-IN				ANT Pin		

Key Features

- Wireless microcontroller
 - Powerful 48-MHz Arm® Cortex®-M33 (CC2674P10) or Cortex®-M4F (CC2652P7) or Cortex®-M4 (CC2651P3) or Cortex®-M4F (CC2652P)
 - 1024kB (CC2674P10) or 704kB (CC2652P7) or 352kB (CC2651P3) or 352KB (CC2652P) flash program memory
 - 8kB of Cache SRAM
 - 296kB (CC2674P10) or 152kB (CC2652P7) or 40kB (CC2651P3) or 88kB (CC2652P) of ultra-low leakage SRAM
 - Dynamic multiprotocol manager (DNM) driver
 - Programmable radio includes support for 2-(G)FSK, 4-(G)FSK, MSK, BLE, IEEE 802.15.4 PHY and MAC
 - Supports over-the-air upgrade (OTA)
- Ultra-Low power sensor controller
 - Autonomous MCU with 4kB of SRAM
- Sample, store, and process sensor data
- Fast wake-up for low-power operation
- Software defined peripherals; capacitive touch, flow meter, LCD
- Low power consumption
 - MCU consumption:
 - ✧ 4.0 mA active mode, CoreMark®
 - ✧ 83 µA/MHz running CoreMark
 - ✧ 1.19 µA standby mode, RTC, 256KB RAM
 - ✧ 0.13 µA shutdown mode, wake-up on pin
 - Ultra Low-power sensor controller consumption:
 - ✧ 30 µA in 2 MHz mode
 - ✧ 809 µA in 24 MHz mode
 - Radio Consumption:
 - ✧ 6.4 mA RX
 - ✧ 7.3 mA TX at 0 dBm
 - ✧ 101 mA TX at +20 dBm
- Wireless protocol support
 - Thread, Zigbee®, Matter

- Bluetooth®5.2 Low Energy
- 6LoWPAN
- Proprietary systems
- High performance radio
 - -104 dBm for Bluetooth® Low Energy 125kbps
 - -105 dBm for IEEE 802.15.4-2006 2.4GHz OQPSK
- Regulatory compliance (On-going)
 - FCC
 - IC
 - CE-RED
- MCU peripherals
 - Most digital peripherals can be routed to any GPIO
 - Four 32-bit or eight 16-bit general-purpose timers
 - 12-bit SAR ADC, 200 ksps, 8 channels
 - 8-bit DAC
 - Two Comparators
 - Programmable current source
 - Four UART, four SPI, two I²C, I²S
 - Real-time clock (RTC)
 - Integrated temperature and battery monitor
- Security enablers
 - Supports secure boot
 - Supports secure key storage and device ID
- Arm TrustZone for trusted execution environment
- AES 128- and 256-bit cryptographic accelerator
- Public key accelerator
- SHA2 accelerator (full suite up to SHA-512)
- True random number generator (TRNG)
- Secure debug lock
- Software anti-rollback protection
- Operating range
 - On-chip buck DC/DC converter
 - 1.8-V to 3.8-V single supply voltage
 - -40 to +85°C
 - -40 to +105°C (-IN variants)
- Antenna:
 - PCB trace antenna, U.FL connector or ANT pin
- Package
 - Dimension: 26 mm x 19 mm x 2.15 mm
 - LCC-42 (30 GPIOs)
 - RoHS-compliant package

Applications

- 2400 to 2480 MHz ISM and SRD systems with down to 4 kHz of receive bandwidth
- Building automation
 - Building security systems – motion detector, electronic smart lock, door and window sensor, garage door system, gateway
 - HVAC – thermostat, wireless environmental sensor, HVAC system controller, gateway
 - Fire safety system – smoke and heat detector, fire alarm control panel (FACP)
 - Video surveillance – IP network camera
 - Elevators and escalators – elevator main control panel for elevators and escalators
- Industrial transport – asset tracking
- Factory automation and control
- Medical
 - Patient monitoring & diagnostics – medical sensor patches, multiparameter patient monitor
 - Medical equipment
 - Home healthcare – blood glucose monitor, pulse oximeter
- Electronic point of sale (EPOS) – Electronic Shelf Label (ESL)
- Communication equipment
 - Wired networking – wireless LAN or Wi-Fi access points, edge router
- Personal Electronics
 - Portable electronics – RF smart remote control
 - Home theater & entertainment – smart speakers, smart display, set-top box
 - Connected peripherals – consumer wiles module, pointing devices, keyboards and keypads

- Gaming – electronic and robotic toys
- Wearables (non-medical) – smart trackers, smart clothing
- Wireless Modules
- Wireless third party modules
- Wireless communications modules

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1. References

- [1] CC2674P10 resources: <https://www.ti.com/product/CC2674P10>
- [2] CC2652P7 resources: <https://www.ti.com/product/CC2652P7>
- [3] CC2651P3 resources: <https://www.ti.com/product/CC2651P3>
- [4] CC2652P resources: <https://www.ti.com/product/CC2652P>

2. Block Diagram

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Figure 2-1. BDE-MP26P Module Block Diagram

3. Terminal Configuration and Functions

3.1. Pin Diagram

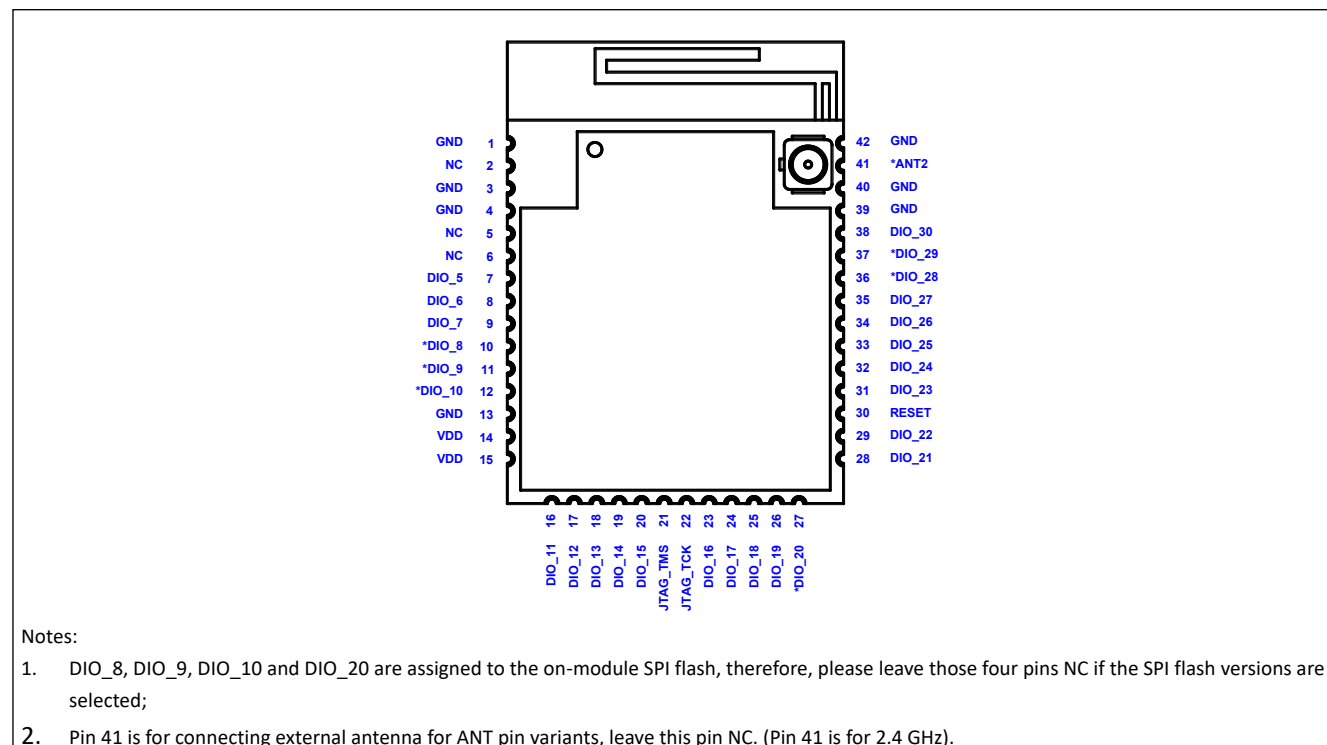


Figure 3-1. Pin Diagram (Top View)

3.2. Pin Attributes and Pin Multiplexing

Table 3-1 describes the definitions of the pins of the module. Pin number of the chip is also stated here, because the VQFN pin is referred to in the software design kit (SDK).

Table 3-1. Pin Description ⁽¹⁾

Module Pin #	Pin Name	Type	Description
1	GND	Ground	Power ground
2	NC	-	No connect
3	GND	Ground	Power ground
4	GND	Ground	Power ground
5	NC	-	No connect
6	NC	-	No connect
7	DIO_5	I/O	GPIO, high-drive capability
8	DIO_6	I/O	GPIO, high-drive capability
9	DIO_7	I/O	GPIO, high-drive capability
10	DIO_8	I/O	GPIO, assigned as SPI_MISO of on-module SPI flash in BDE-MP2674P10X32
11	DIO_9	I/O	GPIO, assigned as SPI_MOSI of on-module SPI flash in BDE-MP2674P10X32

Module Pin #	Pin Name	Type	Description
12	DIO_10	I/O	GPIO, assigned as SPI_SCLK of on-module SPI flash in BDE- MP2674P10X32
13	GND	Ground	Power ground
14	VDD	Power	Power supply
15	VDD	Power	Power supply
16	DIO_11	I/O	GPIO
17	DIO_12	I/O	GPIO
18	DIO_13	I/O	GPIO
19	DIO_14	I/O	GPIO
20	DIO_15	I/O	GPIO
21	JTAG_TMSC	I/O	JTAG TMS, high-drive capability
22	JTAG_TCKC	I	JTAG TCK
23	DIO_16	I/O	GPIO, JTAG_TDO, high-drive capability
24	DIO_17	I/O	GPIO, JTAG_TDI, high-drive capability
25	DIO_18	I/O	GPIO
26	DIO_19	I/O	GPIO
27	DIO_20	I/O	GPIO, assigned as SPI_CS of on-module SPI flash in BDE- MP2674P10X32
28	DIO_21	I/O	GPIO
29	DIO_22	I/O	GPIO
30	RESET	I	Reset, active low, 100K ohm internal pull-up resistor
31	DIO_23	I/O	GPIO, analog capability
32	DIO_24	I/O	GPIO, analog capability
33	DIO_25	I/O	GPIO, analog capability
34	DIO_26	I/O	GPIO, analog capability
35	DIO_27	I/O	GPIO, analog capability
36	DIO_28	I/O	GPIO, analog capability, assigned as RF switch control pin, leave NC
37	DIO_29	I/O	GPIO, analog capability, assigned as RF switch control pin, leave NC
38	DIO_30	I/O	GPIO, analog capability
39	GND	Ground	Power ground
40	GND	Ground	Power ground
41	ANT2	RF	Antenna port for 2.4 GHz
42	GND	Ground	Power ground

4. Specifications

4.1. Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

PARAMETER	MIN	MAX	UNIT	Notes
VDD	-0.3	4.1	V	
Voltage on any digital pins	-0.3	VDD+0.3≤4.1	V	
Voltage on ADC input	-0.3	VDDS	V	Voltage scaling enabled
	-0.3	1.49	V	Voltage scaling disabled, internal reference
	-0.3	VDD/2.9	V	Voltage scaling disabled, VDD as reference
Storage temperature	-40	125	°C	

4.2. Recommended Operating Conditions

PARAMETER	MIN	TYP	MAX	UNIT	NOTE
VDD	1.8	3.3	3.8	V	
	2.3	3.3	3.8	V	SPI flash variants
Operating temperature	-40	-	85	°C	
	-40	-	105	°C	-IN variants
Rising supply voltage slew rate	0		100	mV/μs	
Falling supply voltage slew rate	0		20	mV/μs	

5.1. Dimensions

Top View

Bottom View

Side View

Unit: mm

Fig 5-1. Mechanical Drawing

[illegible]

Fig 5-2. Module Footprint Top View

6. Typical Reflow Profile

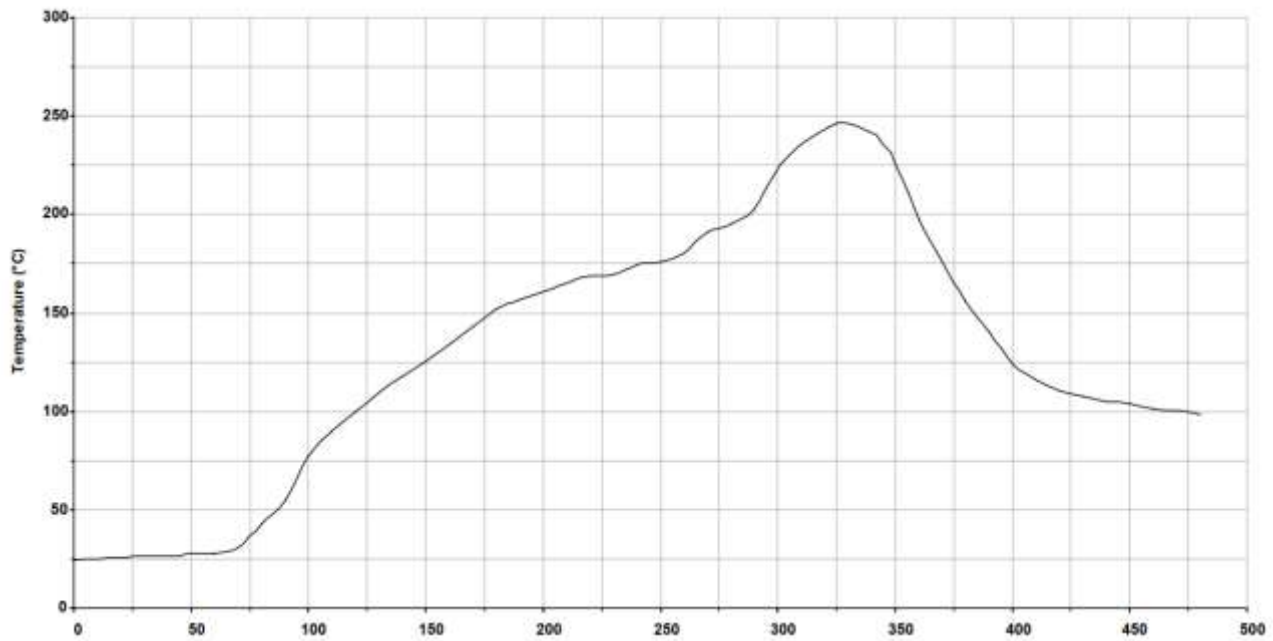


Figure 6-1. Typical Reflow Profile

Key features of the profile:

- Initial ramp = 1-2.5°C/sec to 175°C $\pm$ 25°C equilibrium
- Equilibrium time = 60 to 180 seconds
- Ramp to maximum temperature (245°C) = 3°C/sec max.
- Time above liquidus temperature (217°C): 45-90 seconds
- Device absolute maximum reflow temperature: 260°C

7. Certification

7.1. Regulatory Compliance

The module is certified for FCC, IC/ISED and ETSI/CE as listed in below table. More regions can be cover by request.

Table 7-1. Certification Information

Regulatory Body / Region	ID	MPN
FCC (USA)	2ABRU-MP26P	BDE-MP2674P10A32
IC/ISED (Canada)	25657-MP26P	BDE-MP2674P10U32
ETSI/CE (Europe)	NA	BDE-MP2674P10N32
		BDE-MP2674P10A0
		BDE-MP2674P10U0
		BDE-MP2674P10N0
		BDE-MP2674P10A32-IN
		BDE-MP2674P10U32-IN
		BDE-MP2674P10N32-IN
		BDE-MP2674P10A0-IN
		BDE-MP2674P10U0-IN
		BDE-MP2674P10N0-IN
		BDE-MP2652P7A32
		BDE-MP2652P7U32
		BDE-MP2652P7N32
		BDE-MP2652P7A0
		BDE-MP2652P7U0
		BDE-MP2652P7N0
		BDE-MP2652P7A32-IN
		BDE-MP2652P7U32-IN
		BDE-MP2652P7N32-IN
		BDE-MP2652P7A0-IN
		BDE-MP2652P7U0-IN
		BDE-MP2652P7N0-IN
		BDE-MP2651P3A32
		BDE-MP2651P3U32
		BDE-MP2651P3N32
		BDE-MP2651P3A0
		BDE-MP2651P3U0
		BDE-MP2651P3N0
		BDE-MP2651P3A32-IN

Regulatory Body / Region	ID	MPN
		BDE-MP2651P3U32-IN BDE-MP2651P3N32-IN BDE-MP2651P3A0-IN BDE-MP2651P3U0-IN BDE-MP2651P3N0-IN BDE-MP2652PA32 BDE-MP2652PU32 BDE-MP2652PN32 BDE-MP2652PA0 BDE-MP2652PU0 BDE-MP2652PN0 BDE-MP2652PA32-IN BDE-MP2652PU32-IN BDE-MP2652PN32-IN BDE-MP2652PA0-IN BDE-MP2652PU0-IN BDE-MP2652PN0-IN

7.2. Antenna

Table 7-2. Certified Antenna List

Manufacturer	Manufacturer Part Number	Antenna Type	Frequency Range (MHz)	Gain (dBi)	Note
BDE	BDE-ANT-MB13	PCB trace antenna	2400 - 2450	0.8	Integrated
BDE	BDE-W25-19513-HRP	Whip antenna	2400 - 2500	3.0	External

7.3. FCC Compliance

7.3.1. FCC Statement

This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and,
- (2) This device must accept any interference received, including interference that may cause undesired operation.

7.3.2. FCC Caution

Any changes or modifications to this unit not expressly approved by BDE for compliance could void the user's authority to operate the equipment. The integrator will be responsible to satisfy SAR/RF Exposure requirements, when the module integrated into the host device.

7.3.3. Integration Instructions

List of applicable FCC rules

FCC Part 15.247

Specific operational use conditions

This transmitter/module and its antenna(s) must not be co-located or operating in conjunction with any transmitter. This information also extends to the host manufacturer's instruction manual.

Limited module procedures

Not applicable

Trace antenna designs

Not applicable

RF exposure considerations

This equipment complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This compliance to FCC radiation exposure limits for an uncontrolled environment, and minimum of 20cm separation between antenna and body. The host product manufacturer would provide the above information to end users in their end-product manuals.

Antennas

Refer to Table 7-2

Label and compliance information

The end product must carry a physical label or shall use e-labeling followed KDB784748D01 and KDB784748 stating "Contains Transmitter Module FCC ID: 2ABRU-MP26P".

Information on test modes and additional testing requirements

Contact BDE for more information.

Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is only FCC authorized for the specific rule parts (FCC Part 15.247) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed when contains digital circuitry.

(OEM) Integrator has to assure compliance of the entire end-product that includes the module. For 15 B (§15.107 and if applicable §15.109) compliance, the host manufacturer is required to show compliance with 15 while the module is installed and operating.

Furthermore, the module should be transmitting and the evaluation should confirm that the module's intentional emissions (15C) are compliant (fundamental / out-of-band). Finally, the integrator has to apply the appropriate equipment authorization (e.g. Verification) for the new host device per definition in §15.101. Integrator is reminded to assure that these installation instructions will not be made available to the end-user of the final host device.

7.4. IC/ISED Compliance

7.4.1. IC Statement

This device contains license-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's license-exempt RSS(s). Operation is subject to the following two conditions:

- (1) This device may not cause interference, and,
- (2) This device must accept any interference, including interference that may cause undesired operation of the device.

L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- (1) L'appareil ne doit pas produire de brouillage;
- (2) L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

7.4.2. IC Caution

Any changes or modifications to this unit not expressly approved by BDE for compliance could void the user's authority to operate the equipment. The integrator will be responsible to satisfy SAR/RF Exposure requirements, when the module integrated into the host device.

7.4.3. Integration Instructions

Label and compliance information

The final host device, into which this RF module is integrated has to be labeled with an auxiliary label stating the IC of the RF module, such as "Contains transmitter module IC: 25657-MP26P".

Informations sur l'étiquette et la conformité

Le périphérique hôte final, dans lequel ce module RF est intégré "doit être étiqueté avec une étiquette auxiliaire indiquant le CI du module RF, tel que "Contient le module émetteur IC: 25657-MP26P".

Radio Frequency Exposure Statement for IC

The device has been evaluated to meet general RF exposure requirements. The device can be used in mobile exposure conditions. The min separation distance is 20cm.

Déclaration d'exposition aux radiofréquences pour IC

L'appareil a été évalué pour répondre aux exigences générales en matière d'exposition aux RF. L'appareil peut être utilisé dans des conditions d'exposition mobiles. La distance de séparation minimale est de 20 cm. (TBD)

This radio transmitter [IC: 25657-MP26P] has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed in Table 6, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Cet émetteur radio [IC: 25657-MP26P] a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci-dessous, avec le gain maximal admissible indiqué. Les types d'antenne non inclus dans cette liste qui ont un gain supérieur au gain maximum indiqué pour tout type répertorié sont strictement interdits pour une utilisation avec cet appareil.

7.5. ETSI/CE Compliance

The module is certified with required EU radio and EMC directives. See Table 7-1 for detailed standards the module complies with, or refer to UK Declaration of Conformity.

8. Ordering Information

Part Number	Core Chip	Size (mm)	Operation Temperature	Shipping Form	MOQ
BDE-MP2674P10A32	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2674P10U32	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2674P10N32	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2674P10A0	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2674P10U0	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2674P10N0	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2674P10A32-IN	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2674P10U32-IN	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2674P10N32-IN	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2674P10A0-IN	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2674P10U0-IN	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2674P10N0-IN	CC2674P106TORGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652P7A32	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652P7U32	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652P7N32	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652P7A0	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652P7U0	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652P7N0	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652P7A32-IN	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652P7U32-IN	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652P7N32-IN	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652P7A0-IN	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652P7U0-IN	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652P7N0-IN	CC2652P74TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2651P3A32	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2651P3U32	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2651P3N32	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2651P3A0	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2651P3U0	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2651P3N0	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2651P3A32-IN	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2651P3U32-IN	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2651P3N32-IN	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2651P3A0-IN	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2651P3U0-IN	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2651P3N0-IN	CC2651P31TORGZR	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652PA32	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652PU32	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652PN32	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652PA0	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652PU0	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652PN0	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +85°C	Tape & Reel	1K
BDE-MP2652PA32-IN	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652PU32-IN	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652PN32-IN	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652PA0-IN	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652PU0-IN	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K
BDE-MP2652PN0-IN	CC2652P1FRGZ	26 × 19 × 2.15	-40 to +105°C	Tape & Reel	1K

9. Revision History

Revision	Date	Description
V1.0	8-June-2024	Initial release

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